



## Material Content Data Sheet



<b>Sales Product Name</b>		IPD30N08S2-22		<b>Issued</b>		25. January 2018		
<b>MA#</b>		MA001661984						
<b>Package</b>		PG-TO252-3-11		<b>Weight*</b>		371.44 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.029	1.08	1.08	10846	10846
leadframe	non noble metal	iron	7439-89-6	0.215	0.06		580	
	inorganic material	phosphorus	7723-14-0	0.065	0.02		174	
	non noble metal	copper	7440-50-8	215.017	57.88	57.96	578867	579621
wire	non noble metal	aluminium	7429-90-5	0.925	0.25	0.25	2492	2492
encapsulation	organic material	carbon black	1333-86-4	1.250	0.34		3364	
	plastics	epoxy resin	-	21.868	5.89		58874	
	inorganic material	silicondioxide	60676-86-0	101.843	27.42	33.65	274182	336420
leadfinish	non noble metal	tin	7440-31-5	3.740	1.01	1.01	10069	10069
plating	non noble metal	nickel	7440-02-0	0.091	0.02		244	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	245
solder	noble metal	silver	7440-22-4	0.080	0.02		215	
	non noble metal	tin	7440-31-5	0.064	0.02		172	
	non noble metal	lead	7439-92-1	3.055	0.82	0.86	8223	8610
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		52	
	inorganic material	phosphorus	7723-14-0	0.006	0.00		16	
	non noble metal	copper	7440-50-8	19.177	5.16	5.17	51629	51697
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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